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Continuous Growth with Balanced Portfolio

Revenue

Leader in Respective Area

Key IC Supplier for Mobile Display and Mobile Camera

Mobile DDI

Mobile Image Sensor

* Global Market Share in Revenue, 2016, Company Data
INNOVATIVE PROCESSES

- 32/28nm HKMG: 2010, 1st Foundry Deployment
- 14nm FinFET: 2015, 1st Foundry Deployment
- 10nm FinFET: 2016, 1st Foundry Deployment
- 8nm FinFET: 2018
- 7nm EUV: 2018
- 6nm EUV: 2018

Breaking Through the Limits of Technology

Design Rule (nm)

- 2010
- 2015
- 2016
- 2018
PREMIUM MOBILE SOC

Leading-edge Exynos Series at the Heart of Innovative Mobile Devices

- 2011 Exynos 4412
- 2013 Exynos 5410
- 2014 Exynos 5430
- 2015 Exynos 7420
- 2016 Exynos 8890
- 2017 Exynos 8895

- 32nm HKMG Process
- 28nm 3D FinFET Process
- 20nm
- 14nm
- 10nm

Galaxy S7 edge | S7
Galaxy S6 | S6 edge
Galaxy Note5

Galaxy S8 | S8+
Meizu PRO 6 Plus
Meizu PRO 5
ISOCELL CMOS IMAGE SENSOR
Creating the Innovative Mobile Cameras

Mobile Image Sensor Market Share
Growing Share in Global and China Market

<table>
<thead>
<tr>
<th>Year</th>
<th>Global</th>
<th>China</th>
</tr>
</thead>
<tbody>
<tr>
<td>2015</td>
<td>23%</td>
<td></td>
</tr>
<tr>
<td>2016</td>
<td>32%</td>
<td>43%</td>
</tr>
</tbody>
</table>

* Mobile Phone 5MP & Above Market Only, Market Share in Revenue, Company Data

4X Faster, Accurate AF in Low Light

Dual Pixel Technology
FUTURE MOBILE EXPERIENCE
Enabled by Key Technologies

- Highly Realistic Graphics
- Stunning Photos
- Mobile Healthcare
- Mobile Payment
- Biometric Authentication
- Hub for All Connected Devices
- Intelligent UX
COMPLICATED USER SCENARIOS
Driving Importance of Process and Design Technology

Low Power Consumption
Always Connected, Always On
Long Battery Life

Performance & Design
High Performance CPU/GPU
High Quality Photos, Immersive 3D Video
Large Display in High Resolution
Slim and Sleek Design
LIMITED FOUNDRY SUPPLIERS

14/16nm Foundry Market

- Expected to Grow 2.7X in 2016
- $3B $8B

14/16nm → 20/22nm → 28/32nm

Foundry Service Companies

- Only 4 foundries, including Samsung, can provide leading-edge technology
- 22 Companies
- 4 Companies

Source: Gartner, iSuppli, IBS, IC Insight, Company data
INTEGRATED TOTAL SOLUTIONS

SAMSUNG SYSTEM LSI

Exynos Processor
Modem/RF/Connectivity

ISOCELL
CMOS Image Sensor

Mobile DDI
Touch Controller

NFC/eSE
Fingerprint Sensor

Smart Card

Bio Processor

PMIC
STRATEGY FOR GROWTH

Differentiated Design Technology
- Enhancing Core Competency with Own Designed Unique IPs
- Innovation of Pixel Technologies for Image Sensors

Continuing Process Leadership
- 10nm/7nm Leading-edge Process Design and Manufacturing Capabilities
- Foundry Service to Provide Value-added 28FDSOI/8inch

Customer / Product Diversification
- Greater Presence in China, India Market with Stronger Solutions
- Solutions for Future Applications beyond Mobile
THE WAY TO TOP-CLASS SUPPLIER

Foundry

Strong customer momentum continues with 14nm
→ Renewed longevity with process variations

10nm to be a long-lived node
→ Ramp multiple volume products in 2017

Differentiated solutions with 28FDSOI and 8”
→ Broadening Samsung Foundry offerings
PROCESS LEADERSHIP

Foundry

Performance and Cost Variations
Boosted performance
Reduced layers with same performance with LPP

RF for Connectivity

Ready for Automotive
Supporting AEC-Q100 Grade 2/3
TS16949 qualified (14nm FABs)

Risk Production in 2018
Competitive in power, performance and scaling with EUV

Boosted performance
Reduced layers with same performance with LPP

+14% Boosted Performance
Same Design-rule

+15% Boosted Performance
Same Design-rule

Performance and Cost Variations

Ramp up in 2017 with multiple products

Area Reduction
Easy Migration

Area Reduction
Easy Migration

+10% Boosted Performance
Same Design-rule

+5% Boosted Performance
Same Design-rule

+14% Boosted Performance
Same Design-rule

+5% Boosted Performance
Same Design-rule

+15% Boosted Performance
Same Design-rule

+10% Boosted Performance
Same Design-rule

+5% Boosted Performance
Same Design-rule

14LPC + RF
Process Optimization

+15% Boosted Performance
Same Design-rule
**Technical Leadership**
Technical Leadership with 10nm, Custom CPU and Gigabit LTE Modem

**Differentiation**
14nm Exynos Series for Volume Zone Optimized IC Solution

**Ready for the Future**
Complete Solutions for Wearable / VR / IoT / Automotive
A Mobile Processor that Goes Beyond Mobile Innovation

Exynos series enable new user experience at the heart of the innovative devices.
EXYNOS MODEM
Mobile SOC

Over 280Mpcs Modem Shipment

1st LTE Modem Commercialized


Modem Shipment

Cat. 4 150Mbps
Cat. 6 CA 300Mbps
Cat. 10 3CA 450Mbps
Cat. 12 3CA/ULCA 600Mbps
Cat. 16 5CA 1Gbps

5G

* Source : SA, Air.2017

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SAMSUNG ISOCELL

Image Sensors with unique pixel technologies to bring perfect images anywhere, anytime

<table>
<thead>
<tr>
<th>Bright</th>
<th>Fast</th>
<th>Slim</th>
<th>Dual</th>
</tr>
</thead>
<tbody>
<tr>
<td>Tetracell Smart WDR</td>
<td>DUAL PIXEL</td>
<td>Small Pixel</td>
<td>Dual Camera Solution for Zoom, Depth Sensing, LLS</td>
</tr>
</tbody>
</table>

*LLS (Low Light Shooting)
PROCESS / SERVICE COMPETENCY
ISOCELL CMOS Image Sensor

Advanced Node
28nm based Image Sensors

ISOCELL Pixel Technology
Superior Image Quality with Small Pixel

Custom Design Service
Custom Sensor Design, Software Solution for Dual Camera
SOLUTIONS FOR VR AND WEARABLE

IC Components and Design Reference Platforms for Standalone VRs and Smart Watches

Powered by Exynos VR II

Powered by Exynos W 7270
SOLUTION FOR FUTURE DRIVING

Integrated Technologies for Next Generation In-Vehicle Infotainment and Driving Support System

ISOCELL CMOS Image Sensor for Automotive
- Excellent Low-light Sensitivity Performance
- Maximized HDR 120dB and More
- High Temperature Endurance (AEC-Q100 Grade 2)
- Lowest Dark Current and Read Noise
PACKAGE TECHNOLOGY
Perfect, Optimized Solution to Customer

Integrated Design of Memory, Logic

Full Scoped
Complete Platforms from Conventional to Advanced

Experienced
No.1 PoP Provider
The 1st & No.1 TSV Provider
30 Years Experience

LDP-PoP
Laser Drilled Process Package on Package

SiPed-PoP
System in Packaged Package on Package

FO-PLP
Fan Out Panel Level Package

Simplified Design
Reduced Footprint

Thin
0.9~0.8mm Slim Thickness
Lower Cost, Higher Throughput using Panel Technology

Small

High Bandwidth
High Density

3D Stacking Technology using TSV

Package Solution of Samsung

19/20
Enabling the Future of Mobile through Innovative Technologies

Integrated Solution

Silicon Technology